

# N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

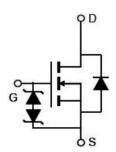
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V <sub>DS min@Tjmax</sub>	710	V
R <sub>DS(ON)TYP</sub>	230	mΩ
ID	14.5	Α
Qg	22	nC



Schematic diagram

## **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE65N260	TO-220-3L	NCE65N260



TO-220

**Absolute Maximum Ratings (Tc=25℃)** 

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	V <sub>DS</sub>	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	14.5	Α
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	10.15	Α
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	43.5	А
Maximum Power Dissipation(Tc=25°C)	P <sub>D</sub>	142	W
Derate above 25°C		0.94	W/°C
Avalanche current <sup>(Note 2)</sup>	I <sub>AS</sub>	3.5	А
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55+175	°C

<sup>\*</sup> limited by maximum junction temperature



## Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	1.05	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	<u>'</u>		•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			100	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±200	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\mu A$	3	3.5	4	٧
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =7A		230	260	mΩ
Dynamic Characteristics			•			
Input Capacitance	C <sub>lss</sub>	V 50VV 0V		1104		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V,		40		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz		3		pF
Total Gate Charge	Qg			22		nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =480 $V$ , $I_{D}$ =7 $A$ ,		7		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		5.5		nC
Gate plateau voltage	Vgp			5.5		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		18		Ω
Switching times			•			
Turn-on Delay Time	t <sub>d(on)</sub>			11		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =480 $V$ , $I_{D}$ =7 $A$ ,		9		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=1.7\Omega, V_{GS}=10V$		57		nS
Turn-Off Fall Time	t <sub>f</sub>			10		nS
Source- Drain Diode Characteristics			•			
Source-drain current(Body Diode)	I <sub>SD</sub>	T 0500			14.5	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			43.5	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =14.5A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T:_05°C ! 7A		240		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I <sub>F</sub> =7A,		2.0		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>	di/dt=100A/μs		17		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, RG=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

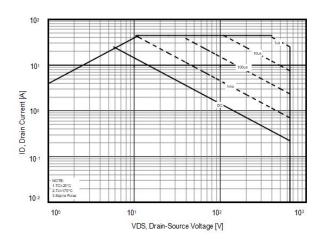


Figure 3. Transfer characteristics

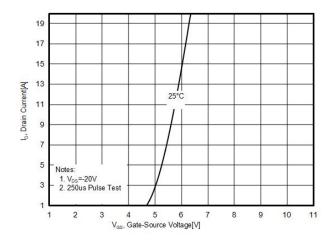


Figure 5. R<sub>DS(ON)</sub> vs Junction Temperature

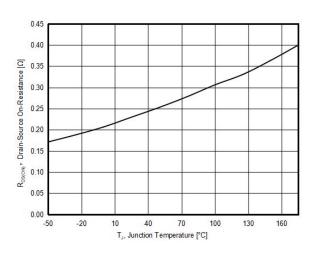


Figure 2. Capacitance

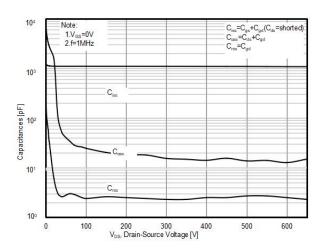


Figure 4. Output characteristics

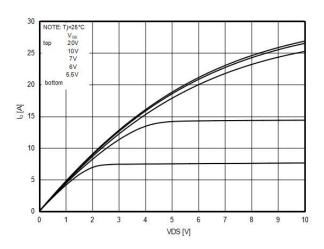


Figure 6. BV<sub>DSS</sub> vs Junction Temperature

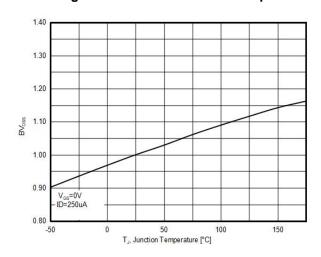




Figure 7. Maximum I<sub>D</sub> vs Junction Temperature

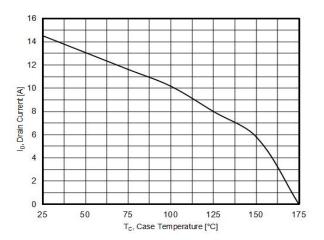


Figure 9. Static drain-source on resistance

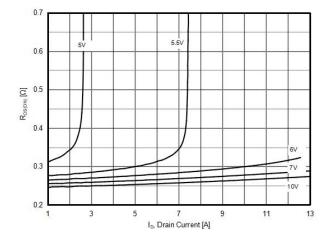


Figure 8. Gate charge waveforms

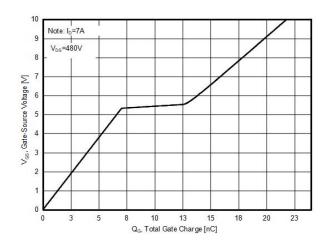
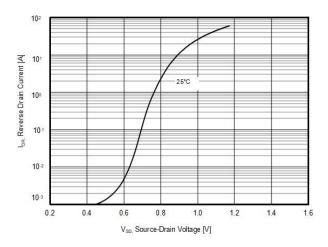


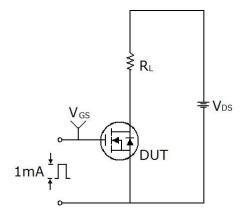
Figure 10. Source-Drain Diode Forward Voltag

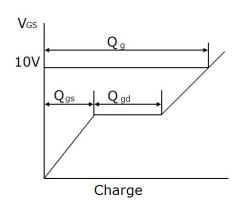




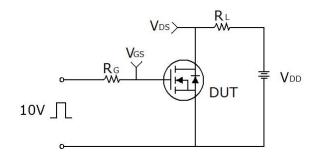
## **Test circuit**

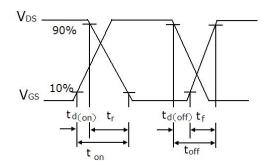
## 1) Gate charge test circuit & Waveform



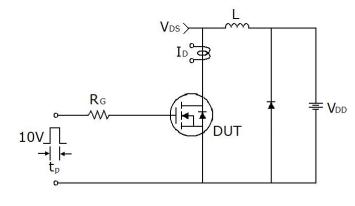


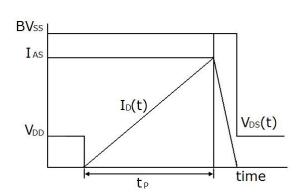
## 2) Switch Time Test Circuit:





## 3) Unclamped Inductive Switching Test Circuit & Waveforms

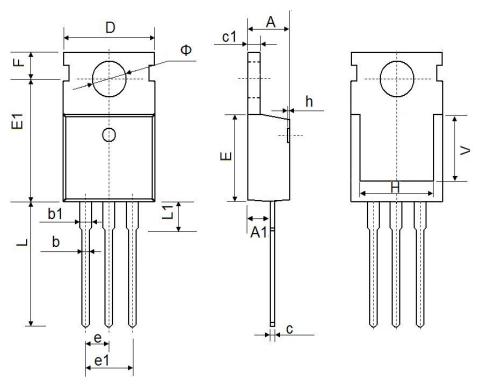






Wuxi NCE Power Co., Ltd

# **TO-220-E Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
А	4.20	4.60	0.165	0.181		
A1	2.25	2.55	0.089	0.100		
b	0.70	0.90	0.028	0.035		
b1	1.17	1.37	0.046	0.054		
С	0.33	0.65	0.013	0.026		
c1	1.20	1.40	0.047	0.055		
D	9.91	10.25	0.390	0.404		
E	8.95	9.75	0.352	0.384		
E1	12.80	12.90	0.504	0.508		
е	2.54	2.54BSC		0.100BSC		
e1	5.08	5.08BSC		)BSC		
F	2.65	2.95	0.104	0.116		
Н	7.90	8.10	0.311	0.319		
L	12.90	13.40	0.508	0.528		
L1	2.85	3.25	0.112	0.128		
Ф	3.40	3.80	0.134	0.150		



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